



Product Change Notification: MFOL-27QONH092

Date:

23-Oct-2024

Product Category:

Clock and Timing - Clock Generation

Notification Subject:

CCB 6457 Final Notice: Qualification of MMT as an additional assembly site for ZL30291LDF1, ZL30291LDG1, ZL30292LDG1 and ZL30292LDF1 catalog part numbers (CPN) available in 100L UQFN (8x8x0.6mm) package.

Affected CPNs:

[**MFOL-27QONH092_Affected_CPN_10232024.pdf**](#)

[**MFOL-27QONH092_Affected_CPN_10232024.csv**](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for ZL30291LDF1, ZL30291LDG1, ZL30292LDG1 and ZL30292LDF1 catalog part numbers (CPN) available in 100L UQFN (8x8x0.6mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (Branch) (MMT)

Wire Material	CuPdAu	CuPdAu	CuPdAu
Die Attach Material	8600	8600	8600
Molding Compound Material	G700LTD	G700LTD	G700LTD
Lead-Frame Material	EFTEC64/C7025	EFTEC64/C7025	EFTEC64T

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 November 2024 (date code: 2447)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2023					>	October 2024				November 2024				
Work Week	27	28	29	30	31		40	41	42	43	44	45	46	47	48
Initial PCN Issue Date				X											
Qual Report Availability											X				
Final PCN Issue Date											X				
Estimated Implementation Date													X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_{#}_Qual_Report.

Revision History: July 28, 2023: Issued initial notification.

October 10, 2024: Issued final notification. Attached the Qualification Report. Updated Pre and Post Change Summary table to remove lead-frame treatment. Provided estimated first ship date to be on November 24, 2024.

October 23, 2024: Re-issued final notification to update Die Attach Material from 3280 to 8600.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-27QONH092_Qualification Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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